

BTA06 T/D/S/A BTB06 T/D/S/A

SENSITIVE GATE TRIACS

FEATURES

■ VERY LOW I_{GT} = 10mA max

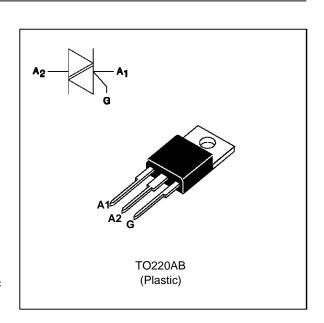
■ LOW I_H = 15mA max

■ BTA Family: INSULATING VOLTAGE = 2500V_(RMS) (UL RECOGNIZED: E81734)

DESCRIPTION

The BTA/BTB06 T/D/S/A triac family are high performance glass passivated PNPN devices.

These parts are suitables for general purpose applications where gate high sensitivity is required. Application on 4Q such as phase control and static switching.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit		
IT(RMS)	RMS on-state current BTA		Tc = 85°C	6	Α
	(360° conduction angle)	втв	Tc = 90°C		
ITSM	Non repetitive surge peak on-state curren	tp = 8.3 ms	63	Α	
	(Tj initial = 25°C)			60	
ı2t	I ² t value tp = 1			18	A2s
dl/dt	Critical rate of rise of on-state current Rep Gate supply : $I_G = 50$ mA $di_G/dt = 0.1$ A/ μ s $F = 0.1$			10	A/μs
		50			
Tstg Tj	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 110	ပို ပိ
TI	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			260	°C

Symbol	Parameter	BTA / BTB06-			
		400 T/D/S/A	600 T/D/S/A	700 T/D/S/A	
VDRM VRRM	Repetitive peak off-state voltage Tj = 110°C	400	600	700	V

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit	
Rth (j-a)	Junction to ambient	60	°C/W	
Rth (j-c) DC	Junction to case for DC	4.4	°C/W	
		втв	3.2	
Rth (j-c) AC	Junction to case for 360° conduction angle	ВТА	3.3	°C/W
	(F= 50 Hz)		2.4	

GATE CHARACTERISTICS (maximum values)

 $P_{G~(AV)} = 1W \qquad P_{GM} = 10W~(tp = 20~\mu s) \qquad I_{GM} = 4A~(tp = 20~\mu s) \qquad V_{GM} = 16V~(tp = 20~\mu s).$

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions		Quadrant		Suffix			Unit	
					Т	D	S	Α	
lGT	$V_D=12V$ (DC) $R_L=33\Omega$	Tj=25°C	1-11-111	MAX	5	5	10	10	mA
			IV	MAX	5	10	10	25	
VGT	$V_D=12V$ (DC) $R_L=33\Omega$	Tj=25°C	I-II-III-IV	MAX		1	.5		V
V _{GD}	V _D =V _{DRM} R _L =3.3kΩ	Tj=110°C	I-II-III-IV	MIN		0.2			V
tgt	$V_D=V_{DRM}$ $I_G=40$ mA $I_G/dt=0.5$ A/ μ s	Tj=25°C	I-II-III-IV	TYP		2			μs
IL	IG= 1.2 I _{GT}	Tj=25°C	I-III-IV	TYP	10	10	20	20	mA
			II		20	20	40	40	
lH *	IT= 100mA gate open	Tj=25°C		MAX	15	15	25	25	mA
VTM *	I _{TM} = 8.5A tp= 380μs	Tj=25°C		MAX	1.65		V		
!DRM	VDRM Rated	Tj=25°C		MAX	0.01		mA		
IRRM	V _{RRM} Rated	Tj=110°C		MAX	0.75				
dV/dt *	Linear slope up to	Tj=110°C		TYP	10	10	-	-	V/μs
	VD=67%VDRM gate open			MIN	-	-	10	10	
(dV/dt)c *	(dl/dt)c = 2.7A/ms	Tj=110°C		TYP	1	1	5	5	V/μs

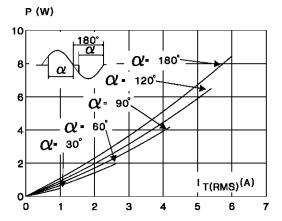
^{*} For either polarity of electrode A₂ voltage with reference to electrode A₁.

ORDERING INFORMATION

Package	l _{T(RMS)}	V _{DRM} / V _{RRM}	Sensitivity Specification			
	Α	V	Т	D	S	Α
ВТА	6	400	Х	Х	Х	Х
(Insulated)		600	X	X	Х	Х
		700	Х	Х	Х	Х
ВТВ		400	Х	Х	Х	Х
(Uninsulated)		600	Х	Х	Х	Х
		700	Х	Х	Х	Х

Fig.1: Maximum RMS power dissipation versus RMS on-state current (F=50Hz). (Curves are cut off by (dl/dt)c limitation)

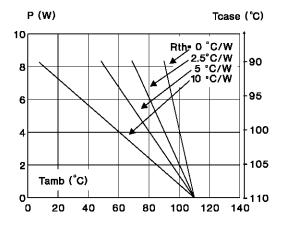
Fig.2: Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTA).

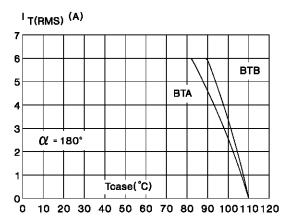


P (W) Tcase (°C) 10 Rthe 0 °C/W 2.5°C/W 85 5 °C/W 8 10 °C/W 90 6 -95 100 105 Tamb (°C) 110 o 20 40 60 80 100 120 140

Fig.3 : Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTB).

Fig.4: RMS on-state current versus case temperature.





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Fig.5: Relative variation of thermal impedance versus pulse duration.

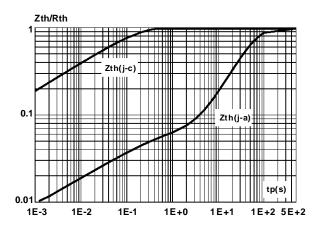


Fig.7 : Non Repetitive surge peak on-state current versus number of cycles.

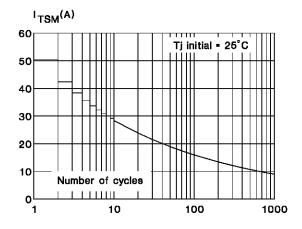


Fig.9: On-state characteristics (maximum values).

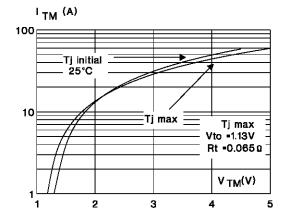


Fig.6: Relative variation of gate trigger current and holding current versus junction temperature.

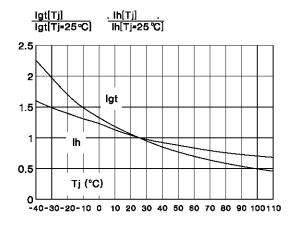
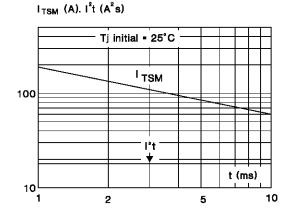
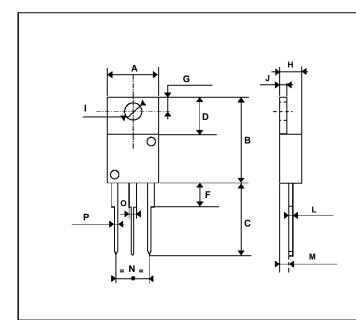


Fig.8 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \le 10ms$, and corresponding value of l^2t .



PACKAGE MECHANICAL DATA

TO220AB Plastic



REF.	DIMENSIONS			
	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
Α	10.20	10.50	0.401	0.413
В	14.23	15.87	0.560	0.625
С	12.70	14.70	0.500	0.579
D	5.85	6.85	0.230	0.270
F		4.50		0.178
G	2.54	3.00	0.100	0.119
Н	4.48	4.82	0.176	0.190
I	3.55	4.00	0.140	0.158
J	1.15	1.39	0.045	0.055
L	0.35	0.65	0.013	0.026
М	2.10	2.70	0.082	0.107
N	4.58	5.58	0.18	0.22
0	0.80	1.20	0.031	0.048
Р	0.64	0.96	0.025	0.038

Cooling method: C Marking: type number

Weight: 2.3 g

Recommended torque value : 0.8 m.N. Maximum torque value : 1 m.N.

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